P-Ch MOSFET

General Description

The WSD30L90DN56 is the highest performance trench P-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD30L90DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

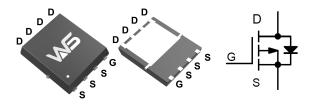
Product Summery

BVDSS	RDSON	ID
-30V	6.4mΩ	-90A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN5X6-8 Pin Configuration



Absolute Maximum Ratings

		Rating		
Symbol	Parameter	10s	Steady State	Units
V _{DS}	Drain-Source Voltage		30	V
V_{GS}	Gate-Source Voltage	<u>+</u>	25	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-6	90	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹		-57	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-27	-22	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-24	-19	Α
I _{DM}	Pulsed Drain Current ²	-360		А
EAS	Single Pulse Avalanche Energy ³		88	
I _{AS}	Avalanche Current		12	А
P _D @T _C =25℃	Total Power Dissipation ⁴ 40		W	
P _D @T _A =25℃	Total Power Dissipation ⁴	6.3	6.15	W
T _{STG}	Storage Temperature Range	-55 t	-55 to 150	
TJ	Operating Junction Temperature Range	-55 t	-55 to 150	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		50	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		20	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		1.6	°C/W



P-Ch MOSFET

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =-1mA		-0.0332		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-25A		5.2	6.4	
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-10A		8.6	12	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-1.3	-1.8	-2.3	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		4.4		mV/℃
	Drain Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			-1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55℃			-5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		28		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2	5	Ω
Q_g	Total Gate Charge (-4.5V)			70		
Q_gs	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-10V , I _D =-25A		10		nC
Q _{gd}	Gate-Drain Charge			18		
T _{d(on)}	Turn-On Delay Time			15		
Tr	Rise Time	V_{DD} =-15V , V_{GEN} =-10V , R_G =6 Ω		19		20
T _{d(off)}	Turn-Off Delay Time	I _D =-1A ,RL=15Ω		88		ns
T _f	Fall Time			62		
Ciss	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		3200		
C _{oss}	Output Capacitance			640		pF
C _{rss}	Reverse Transfer Capacitance			600		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.5mH , I _{AS} =-36A	88			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V -V -0V Force Current			-45	Α
I _{SM}	Pulsed Source Current ^{2,6}	$V_G=V_D=0V$, Force Current			-300	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1	V
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		30		nS
Qrr	Reverse Recovery Charge	T _J =25°C		14		nC

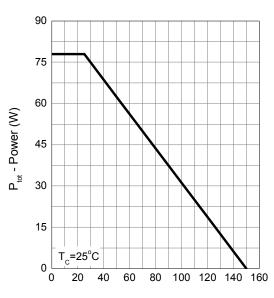
Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.5mH,I_{AS}=-36A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



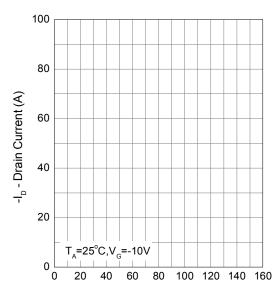
Typical Characteristics

Power Dissipation



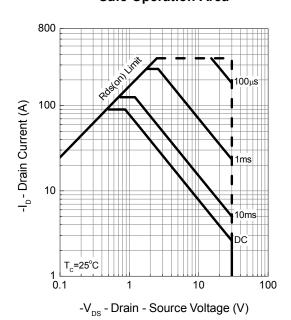
T_i - Junction Temperature (°C)

Drain Current

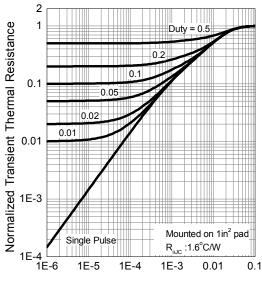


T_i - Junction Temperature (°C)

Safe Operation Area



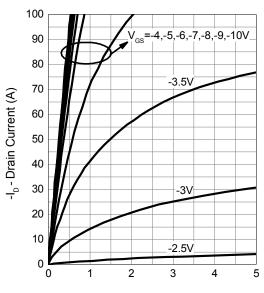
Thermal Transient Impedance



Square Wave Pulse Duration (sec)

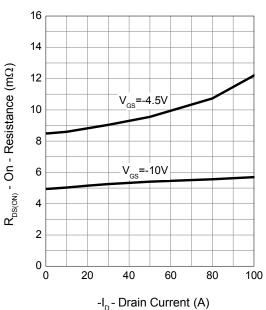


Output Characteristics



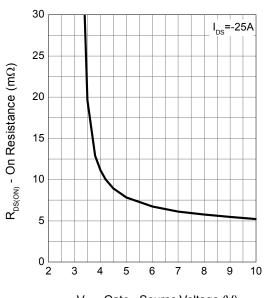
 $-V_{DS}$ - Drain-Source Voltage (V)

Drain-Source On Resistance



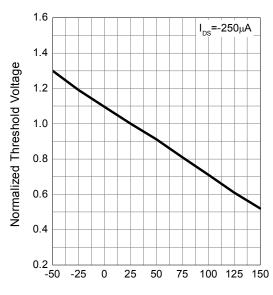
ID Brain Ganerii (71)

Gate-Source On Resistance



-V_{GS} - Gate - Source Voltage (V)

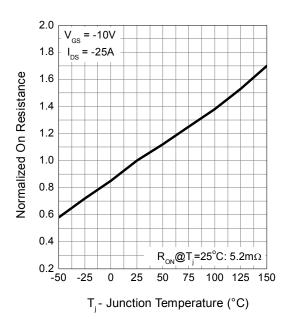
Gate Threshold Voltage



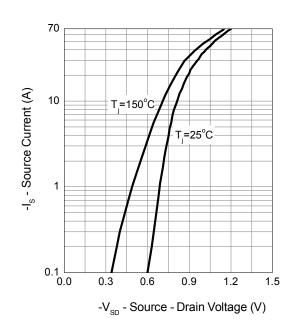
 T_{j} - Junction Temperature (°C)



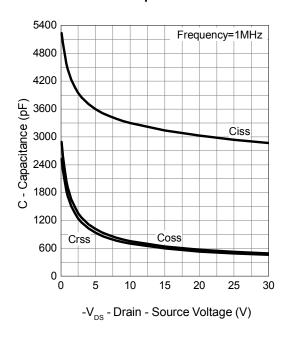
Drain-Source On Resistance



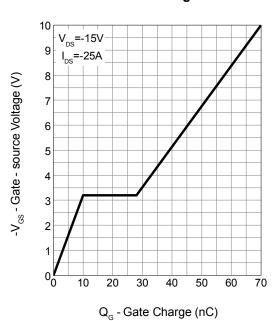
Source-Drain Diode Forward



Capacitance



Gate Charge





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